

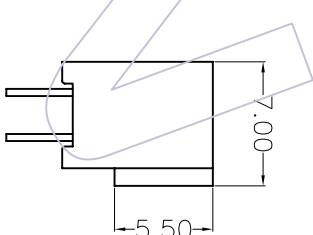
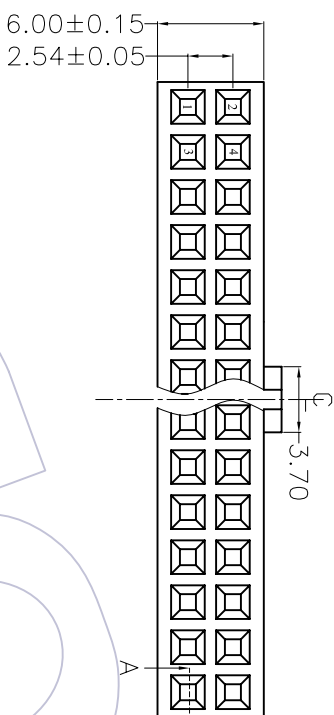
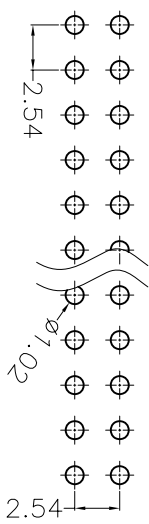
# HSP

**NOTES:**

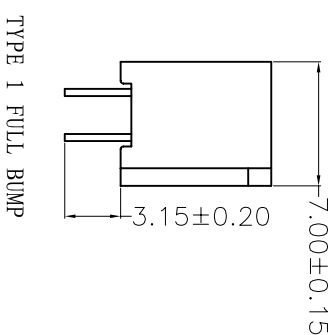
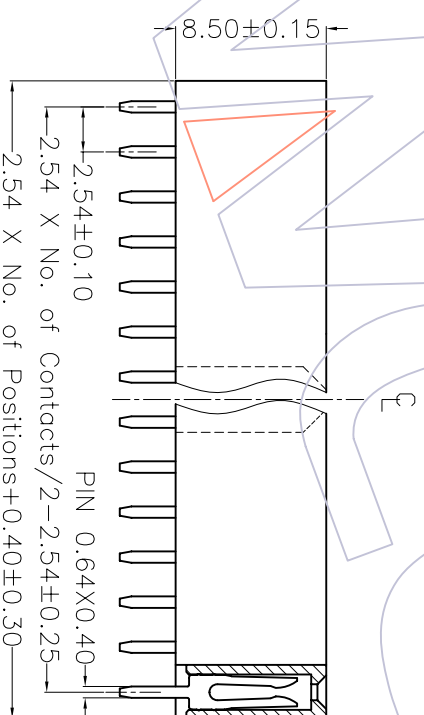
Current Rating: 3.0AMP  
 Withstand Voltage: 500V AC/DC  
 Contact Resistance: 20mΩ Max  
 Insulation Resistance: 1000MΩMin  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze or Brass  
 Contact plating: Au or Sn over Ni  
 Insulator Material: PBT or PA6T+30%G.F UL94V-0

Recommended P.C.B Layout(TOP Side)  
 (PCB BOARD TOLERANCE±0.05)



TYPE 2 HALF BUMP



TYPE 1 FULL BUMP

## Ordering Information

2185-2XX S XX X YN A X

No. of Pins per ROW: 42-40PIN  
 Contact Plating: Insulator: A=193T T=Tube  
 G0=Gold Flash A=193T T=Tube  
 G1=3µ"Gold C=PA6T A=Tray  
 G2=5µ"Gold  
 G3=10µ"Gold  
 G4=15µ"Gold  
 G5=30µ"Gold  
 S0=Gold Flash/Tin  
 S1=3µ"Gold/Tin  
 S2=5µ"Gold/Tin  
 S3=10µ"Gold/Tin  
 S4=15µ"Gold/Tin  
 S5=30µ"Gold/Tin  
 SN=Tin

SECTION: A-A

TYPE	PART NO.
TYPE 1	2185-2XXSXXYYNA3
TYPE 2	2185-2XXSXXYYNA4

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	OPERATION	DRAW	WEIXD	08.03.13	SCALE	3:1	UNIT	mm	PART NO.	SEE TABLE
A0	08/03/13	NEW			X.X	DESIGN			A4	1/1			PH2.54 DUAL 180° H=8.50 WITH BUMP	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle	CHECK			PROJ.				Customer NO.	
1					± .3°	APPROVE								

**WCON** 维峰五金电子有限公司  
 WAVE HARDWARE ELECTRONICS CO. LTD